

TITLE

VOLATILE COPPER(I) COMPLEXES FOR DEPOSITION OF COPPER  
FILMS BY ATOMIC LAYER DEPOSITION

ABSTRACT

5           The present invention relates to novel 1,3-diimine copper  
complexes and the use of 1,3-diimine copper complexes for the deposition  
of copper on substrates or in or on porous solids in an Atomic Layer  
Deposition process.

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BCS/dmm